

ULTRA LOW CAPACITANCE TVS ARRAY



DESCRIPTION

The GBLCxx and GBLCxxC Series are ultra low capacitance transient voltage suppressor arrays, designed to protect applications such as portable electronics and SMART phones. This series is available in both unidirectional and bidirectional configurations and is rated at 350 Watts for an 8/20µs waveshape.

The GBLCxx and GBLCxxC Series meets IEC 61000-4-2 (ESD) and IEC 61000-4-4 (EFT) requirements. At higher operating frequencies or faster edge rates, insertion loss and signal integrity are a major concern. This series offers a ultra low capacitance and low leakage current in a miniature SOD-323 package.

FEATURES

- Compatible with IEC 61000-4-2 (ESD): Air ±15kV, Contact ±8kV
 Exceeds Level 4: Handles 20kV Contact & 25kV Air Discharge
- Compatible with IEC 61000-4-4 (EFT): 40A 5/50ns
- Compatible with IEC 61000-4-5 (Surge)
- Compatible with ISO 10605 (ESD): 330pF/2k Ω , ±20kV Contact
- 350 Watts Peak Pulse Power per Line (tp = 8/20μs)
- · Replacement for MLV (0805)
- Unidirectional & Bidirectional Configuration
- Protects One Power or I/O Port
- ESD Protection > 25kV
- Low Clamping Voltage
- · Available in Multiple Voltages Ranging From 3V to 24V
- Ultra Low Capacitance: 3pF (Typical)
- · RoHS Compliant
- REACH Compliant

MECHANICAL CHARACTERISTICS

- Molded JEDEC SOD-323 Package
- Approximate Weight: 5 milligrams
- Lead-Free Pure-Tin Plating (Annealed)
- Solder Reflow Temperature:

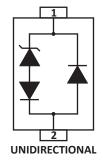
Pure-Tin - Sn, 100: 260-270°C

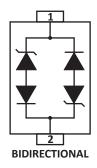
- 8mm Tape and Reel Per EIA Standard 481
- Flammability Rating UL 94V-0

APPLICATIONS

- Ethernet 10/100/1000 Base T
- SMART Phones
- Handheld Wireless Systems
- USB Interface

PIN CONFIGURATIONS





TYPICAL DEVICE CHARACTERISTICS

MAXIMUM RATINGS @ 25°C Unless Otherwise Specified								
PARAMETER	SYMBOL	VALUE	UNITS					
Peak Pulse Power (tp = 8/20μs) - See Figure 1	P _{pp}	350	Watts					
Operating Temperature	T _A	-55 to 150	°C					
Storage Temperature	T _{stg}	-55 to 150	°C					

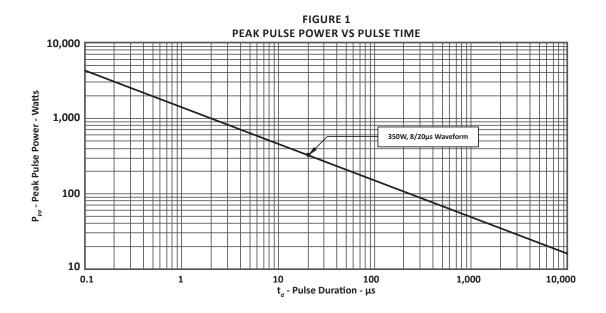
ELECTRICAL CHARACTERISTICS PER LINE @ 25°C Unless Otherwise Specified									
PART NUMBER (Note 1 -2)	DEVICE MARKING	RATED STAND-OFF VOLTAGE V _{WM} VOLTS	MINIMUM BREAKDOWN VOLTAGE @ 1mA V _(BR) VOLTS	MAXIMUM CLAMPING VOLTAGE (Fig. 2) @ IP = 1A V _c VOLTS	MAXIMUM LEAKAGE CURRENT @V _{wM} I _D μΑ	TYPICAL CAPACITANCE @0V, 1MHz C pF			
GBLC03	3	3.3	4.0	7.0	5	3			
GBLC03C	3C	3.3	4.0	7.0	5	3			
GBLC05	5	5.0	6.0	9.8	5	3			
GBLC05C	5C	5.0	6.0	9.8	5	3			
GBLC08	8	8.0	8.5	13.4	2	3			
GBLC08C	8C	8.0	8.5	13.4	2	3			
GBLC12	2	12.0	13.3	19.0	1	3			
GBLC12C	2C	12.0	13.3	19.0	1	3			
GBLC15	6	15.0	16.7	24.0	1	3			
GBLC15C	6C	15.0	16.7	24.0	1	3			
GBLC18	1	18.0	20.0	29.0	1	3			
GBLC18C	1C	18.0	20.0	29.0	1	3			
GBLC24	4	24.0	26.7	43.0	1	3			
GBLC24C	4C	24.0	26.7	43.0	1	3			

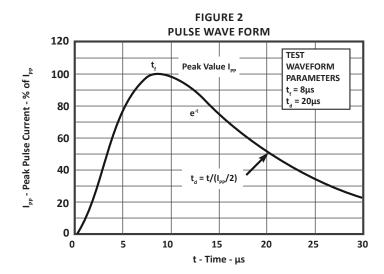
NOTES

^{1.} Part numbers with an additional "C" suffix are bidirectional devices, i.e., GBLC05 $\underline{\textbf{C}}$.

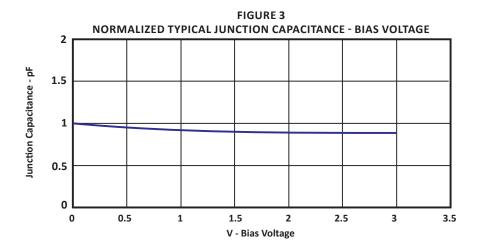
^{2.} Unidirectional Only: Positive potential is applied from pin 1 to 2.

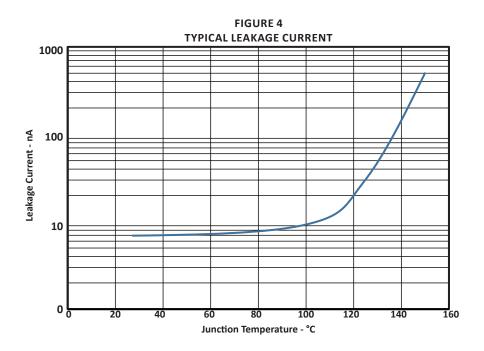
TYPICAL DEVICE CHARACTERISTICS





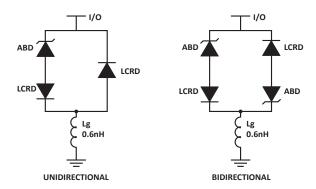
TYPICAL DEVICE CHARACTERISTICS





SPICE MODEL

FIGURE 1 SPICE MODEL



ABD - Avalanche Breakdown Diode (TVS) LCRD: Low Capacitance Rectifier Diode Lg - Lead Inductance

TABLE 1 - SPICE PARAMETERS								
PARAMETER	UNIT	ABD(TVS)	LCRD					
BV	V	See Table 2	200					
IBV	μΑ	1	0.01					
C _{jo}	pF	See Table 2	2					
I _s	А	See Table 2	1E-11					
Vj	V	0.6	0.6					
М	-	0.33	0.33					
N	-	1	1					
R _s	Ohms	See Table 2	0.75					
TT	s	1E-8	1E-9					
EG	eV	1.11	1.11					

TABLE 2 - ABD SPECIFIC SPICE PARAMETERS								
PART NUMBER	B _v (VOLTS)	C _{io} (pF)	I _s (AMPS)	Rs(OHMS)				
GBLC03 & GBLC03C	4.0	10	1E-11	0.21				
GBLC05 & GBLC05C	6.0	284	1E-11	0.14				
GBLC08 & GBLC08C	8.5	146	1E-11	0.28				
GBLC12 & GBLC12C	13.3	123	1E-13	0.40				
GBLC15 & GBLC15C	16.7	102	1E-13	0.52				
GBLC18 & GBLC18C	20.0	80	1E-13	0.80				
GBLC24 & GBLC24C	26.7	61	1E-13	1.54				



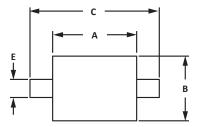


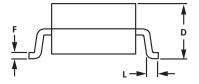
SOD-323 PACKAGE INFORMATION

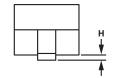
OUTLINE DIMENSIONS								
DIM	MILLIN	IETERS	INCHES					
	MIN	MAX	MIN	MAX				
А	1.60	1.90	0.063	0.075				
В	1.15	1.45	1.45 0.045					
С	2.39	2.70	0.094	0.106				
D	0.80	1.10	0.031	0.043				
Е	0.25	0.40	0.010	0.016				
F	0.10	0.20	0.004	0.008				
Н	-	0.10	-	0.004				
L	0.20	-	0.008	-				

NOTES

- 1. Controlling dimension: millimeters.
- 2. Dimensioning and tolerances per ANSI Y14.5M, 1985.
- 3. Dimensions are exclusive of mold flash and metal burrs.



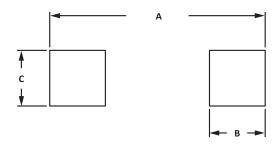




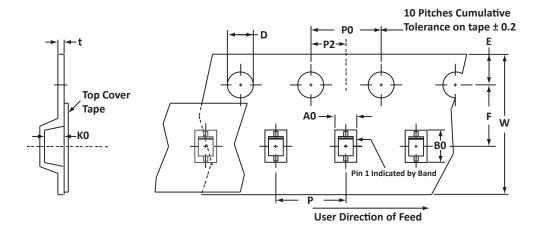
PAD LAYOUT DIMENSIONS								
DINA	MILLIM	IETERS	INCHES					
DIM	MIN	MAX	MIN	MAX				
Α	2.87	3.12	0.113	0.123				
В	0.66	0.91	0.026	0.036				
С	0.66	0.91	0.026	0.036				

NOTES

1. Controlling dimension: millimeters.



TAPE AND REEL



SPECIFICATIONS												
REEL DIA.	TAPE WIDTH	A0	В0	КО	D	E	F	W	P0	P2	Р	tmax
178mm (7")	8mm	1.55 ± 0.10	2.90 ± 0.10	1.35 ± 0.10	1.50 ± 0.10	1.75 ± 0.10	3.50 ± 0.05	8.00 ± 0.30	4.00 ± 0.10	2.00 ± 0.05	4.00 ± 0.10	0.25

NOTES

- 1. Dimensions are in millimeters.
- 2. Surface mount product is taped and reeled in accordance with EIA-481.
- 3. Suffix T7 = 7" Reel 3,000 pieces per 8mm tape.
- 4. Marking on Part marking code (see page 2), polarity band (Unidirectional Only).

ORDERING INFORMATION									
BASE PART NUMBER (xx = Voltage)	LEADFREE SUFFIX	TAPE SUFFIX	QTY/REEL	REEL SIZE	TUBE QTY				
GBLCxx/GBLCxxC	-LF	-T7	3,000	7"	n/a				
This device is only available in a Lead-Free configuration.									

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COMPANY INFORMATION

COMPANY PROFILE

In business more than 25 years, ProTek Devices™ is a privately held semiconductor company. The company offers a product line of overvoltage protection and overcurrent protection components. These include transient voltage suppressor array (TVS arrays) avalanche breakdown diode, steering diode TVS array and electronics SMD chip fuses. These components deliver circuit protection in electronic systems from numerous overvoltage and overcurrent events. They include lightning; electrostatic discharge (ESD); nuclear electromagnetic pulses (NEMP); inductive switching; and electromagnetic interference (EMI) / radio frequency interference (RFI). ProTek Devices also offers LED wafer die for ESD protection and related high frequency products. ProTek Devices is ISO 9001:2015 certified.

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